| Reg. No.: |  |  |  |  |  |
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## **Question Paper Code: 46404**

## B.E. / B.Tech. DEGREE EXAMINATION, DEC 2021

Sixth Semester

## **Electronics and Communication Engineering**

|  |                 |                    | 2.1.8.1.1.1.1.18  |                       |      |  |
|--|-----------------|--------------------|---|-----------------------|------|--|
|  | 14UEC60         | 04-VLSI DESI       | GN  |                       |      |  |
|  | (Reg            | gulation 2014)     |   |                       |      |  |
| Duration: Three hours  |                 |                    |   | Maximum: 100 Ma       | ırks |  |
|  | Answer          | ALL Question       | ns  |                       |      |  |
| (Smith chart may be permitted)   |                 |                    |   |                       |      |  |
|  | PART A -        | (10  x  1 = 10  M) | larks)  |                       |      |  |
| 1. VLSI technology uses  | to              | form integrate     | ed circuit.   |                       |      |  |
| (a) Transistors  | (b) Switches    | (c) Diodes         | (d) Buffers   | S                     |      |  |
| 2. The difficulty in achiev  | ving high dopin | g concentration    | n leads to  |                       |      |  |
| <ul><li>(a) Error in concentration</li><li>(c) Error in doping</li></ul> |                 |                    | <ul><li>(b) Error in variation</li><li>(d) Distribution</li></ul> |                       |      |  |
| 3. In accordance to the sc   | aling technolog | y, the total de    | lay of the log  | ic circuit depends or | 1    |  |

- (a) The capacitor to be charged
- (b) The voltage through which capacitance must be charged
- (c) Available current
- (d) All of the above

| 4. | In CMOS circuits, which current & discharging of   | • • •   | •                                 | lue to switching of transient                             |  |  |  |  |
|----|--|---|-----------------------------------|---|--|--|--|--|
|    | (a) Static dissipatio  | n   | (b) Dynamic                       | dissipation   |  |  |  |  |
|    | (c) Both a and b   |   | (d) None of the above             |   |  |  |  |  |
| 5. | The output of latches w  (a) The trigger puls  (b) Any pulse given  (c) They don't get a  (d) None of the Me | e is given to cha<br>to go into previ<br>any pulse more | ange the state                    |   |  |  |  |  |
| 6. | The sequential circuit is  | also called   |                                   |   |  |  |  |  |
|    | (a) Flip-flop  | (b) Latch   | (c) Strobe                        | (d) None of the Mentioned                                 |  |  |  |  |
| 7. | Boundary scan test is us   | sed to test   |                                   |   |  |  |  |  |
|    | (a) Pins   | (b) Multiplie   | rs (c) Boards                     | (d) wires   |  |  |  |  |
| 8. | CMOS domino logic od   | ccupies   |                                   |   |  |  |  |  |
|    | (a) Smaller area   |   | (b) Larger area                   | ı   |  |  |  |  |
| 9. | (c) Both of the ment<br>Test Benches procedur  |   | (d) None of th                    | e mentioned   |  |  |  |  |
|    | (a) Smaller design   |   | (b) Larger des                    | ign   |  |  |  |  |
| 10 | (c) Complicated  D. Blocking & Non blocking  | ing assignment  | (d) None of the                   | mentioned   |  |  |  |  |
|    | <ul><li>(a) =statement &amp; ≤</li><li>(c) Statement</li></ul>   | statement   | ` '                               | (b) $\leq$ statement<br>(d) $\geq$ statement & =statement |  |  |  |  |
|    |  | PART - B (  | $(5 \times 2 = 10 \text{ Marks})$ |   |  |  |  |  |
| 11 | . What is Body effect and  | d channel Lengt   | h modulation?                     |   |  |  |  |  |
| 12 | 2. Define design margin.   |   |                                   |   |  |  |  |  |
| 13 | 3. Draw the pseudo nmos  | inverter.   |                                   |   |  |  |  |  |
| 14 | What is stuck – at fault   | ?   |                                   |   |  |  |  |  |
| 15 | 6. What is the structural g  | ate-level model   | ing?                              |   |  |  |  |  |

## PART - C (5 x 16 = 80 Marks)

| 16. | (a) | Explain layout design rules in detail.   | (16)               |
|-----|-----|--|--------------------|
|     |     | Or   |                    |
|     | (b) | Explain in detail about region and modes of operations in MOSFET.  | (16)               |
| 17. | (b) | Explain in detail about delay estimation, logical effort and transistor sizing with example.  Or  Explain the static and dynamic power dissipation in CMOS circuits with necessa diagrams and expressions. | (16)<br>ry<br>(16) |
| 18. | (a) | Explain in detail: (i) Conventional CMOS Latch (ii) Conventional CMOS Flip   | flop.<br>(16)      |
|     |     | Or   |                    |
|     | (b) | Explain in detail about sequencing dynamic circuits and synchronizers.   | (16)               |
| 19. | (a) | What are the various testing methods to be considered while designing a circuit?   | VLSI<br>(16)       |
|     |     | Or   |                    |
|     | (b) | Explain in detail about silicon debug principles.  | (16)               |
| 20. | (a) | Explain the concept involved in structural gate level modeling and also give description for Decoder and parity encoder.   | e the<br>(16)      |
|     |     | Or   |                    |
|     | (b) | Explain the looping statements and procedural assignments in VERILOG HDL.  | (16)               |
|     |     |  |                    |